PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kaoru KATOH	10/16/2009
Shigeki KOYA	10/16/2009
Shinichiro TAKATANI	10/16/2009
Yasushi SHIGENO	10/16/2009
aKISHIGE NAKAJIMA	10/16/2009
Takashi OGAWA	10/16/2009

RECEIVING PARTY DATA

Name:	Renesas Technology Corp.
Street Address:	6-2, Otemachi 2-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12615525

CH $40.00 12615525

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	XA-11474/T3662-17515US01
NAME OF SUBMITTER:	Mitchell W. Shapiro

Total Attachments: 2
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ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by RENESAS TECHNOLOGY CORP., a corporation organized under the laws of Japan, located at 6-2 , Otemachi 2-chome , Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said RENESAS TECHNOLOGY CORP., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT AND HIGH FREQUENCY MODULE WITH THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP.,

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Kaoru Katoh (Kaoru KATOH)	10/16/2009
2)	Shigeki Koya (Shigeki KOYA)	10/16/2009
3)	(Shinichiro TAKATANI)	
4)	Yasushi Shigeno (Yasushi SHIGENO)	10/16/2009
5)	Akishige Nakajima (Akishige NAKAJIMA)	10/16/2009
6)	Takashi Ogawa (Takashi OGAWA)	10/16/2009
7)		

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(譲 渡 証)

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP.,

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) (Kaoru KATOH)	
2) (Shigeki KOYA)	
3) (Shinichiro TAKATANI)	10/30/2009
4) (Yasushi SHIGENO)	
5) (Akishige NAKAJIMA)	
6) (Takashi OGAWA)	
7)	